

P-Channel Enhancement Power MOSFET

1. Product Information

Features

Advanced trench technology
Excellent $R_{DS(ON)}$
Low gate charge

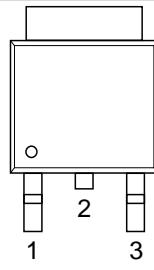
Pin Description

Pin	Description
1	Gate(G)
2	Drain(D)
3	Source(S)

Applications

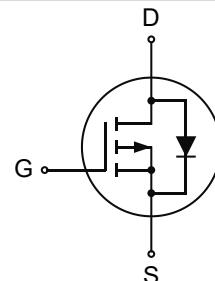
Synchronous Rectification
DC-DC Converters

Simplified Outline



Top View
TO-252

Symbol



Quick reference

$V_{DS} = -30V$
 $I_D = -80A$
 $R_{DS(ON)} \leq 7.5m\Omega$ @ $V_{GS}=-10V$ (Type: $6.3m\Omega$)
 $R_{DS(ON)} \leq 12m\Omega$ @ $V_{GS}=-4.5V$ (Type: $10m\Omega$)

Package Marking and Ordering Information

Product Name	Package	Marking	Reel Size	Tape Width	Quantity
KJ80P03K	TO-252	KJ80P03K	-	-	2500

2. Absolute Maximum Ratings ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Values	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0V$)	-30	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current @ $T_c=25^\circ C$	-80	A
	Continuous Drain Current @ $T_c=100^\circ C$	-63	A
I_{DM} ¹	Pulsed Drain Current	-360	A
E_{AS} ²	Single Pulse Avalanche Energy	135	mJ
I_{AS}	Avalanche Current	-30	A
P_D ³	Power Dissipation @ $T_c=25^\circ C$	50	W
	Power Dissipation @ $T_c=100^\circ C$	39.5	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55~175	°C
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	62.5	°C/W
$R_{\theta JC}$	Thermal Resistance from Junction to Case	2.5	°C/W

3. Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, T_J=25^\circ\text{C}$	-	-	-1	μA
		$V_{\text{DS}}=-30\text{V}, V_{\text{GS}}=0\text{V}, T_J=100^\circ\text{C}$	-	-	-25	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{DS}}=0\text{V}, V_{\text{GS}}=\pm 20\text{V}$	-	-	± 100	nA
$V_{\text{GS(th)}}$	Gate-Source Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1.0	-1.7	-2.4	V
$R_{\text{DS(on)}}^3$	Drain-Source On-Resistance	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-20\text{A}$	-	6.3	7.5	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-20\text{A}$	-	10	12	$\text{m}\Omega$
g_{fs}^3	Forward Transconductance	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-20\text{A}$	30	-	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=-15\text{V}, f=1.0\text{MHz}$	-	4942	-	pF
C_{oss}	Output Capacitance		-	473	-	
C_{rss}	Reverse Transfer Capacitance		-	461	-	
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DD}}=-15\text{V}, I_{\text{D}}=-20\text{A}, R_{\text{G}}=2.5\Omega$	-	182	-	ns
t_{r}	Turn-on Rise Time		-	262	-	
$t_{\text{d(off)}}$	Turn-off Delay Time		-	1.3	-	
t_{f}	Turn-off Fall Time		-	9.8	-	
Gate Charge Characteristics						
Q_{g}	Total Gate Charge	$V_{\text{DD}}=-15\text{V}, V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-20\text{A}$	-	82	-	nC
Q_{gs}	Gate-Source Charge		-	14	-	
Q_{gd}	Gate-Drain Charge		-	16	-	
Diode Characteristics						
I_{s}	Continuous Body Diode Current	$T_c=25^\circ\text{C}$	-	-	-80	A
I_{SM}	Pulse Diode Forward Current	$T_c=25^\circ\text{C}$	-	-	-360	A
V_{SD}	Body Diode Voltage	$T_J=25^\circ\text{C}, I_{\text{SD}}=-15\text{A}, V_{\text{GS}}=0\text{V}$	-	-	-1.2	V
T_{rr}	Reverse Recovery Time	$I_F=-15\text{A}, dI_F/dt=100\text{A}/\mu\text{s}$	-	34	-	ns
Q_{rr}	Reverse Recovery Charge		-	79	-	nC

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. $I_{\text{AS}}=-30\text{A}, L=0.3\text{mH}, V_{\text{DD}}=30\text{V}, R_{\text{G}}=25\Omega$, Starting $T_J=25^\circ\text{C}$
3. Pulse test: Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$

4. Typical Characteristics

Figure 1. Output Characteristics

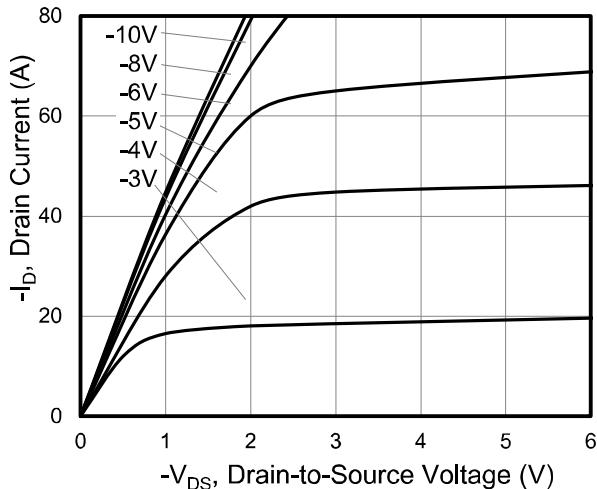


Figure 2. Transfer Characteristics

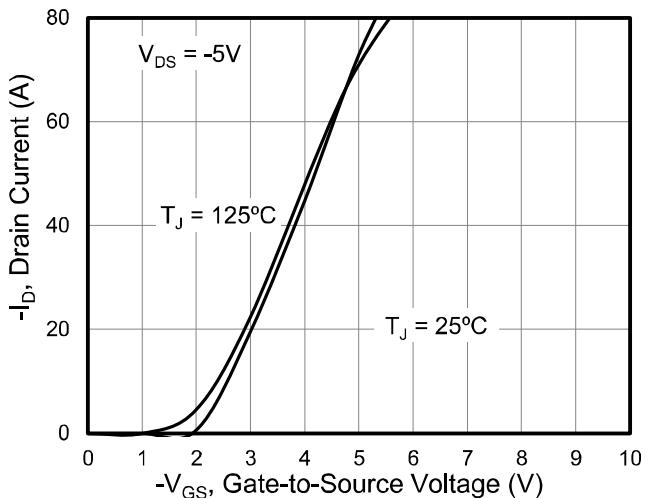


Figure 3. On-Resistance vs. Drain Current

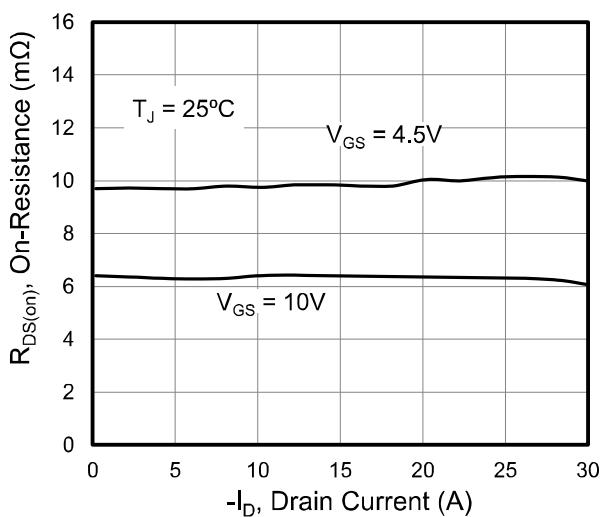


Figure 4. Capacitance

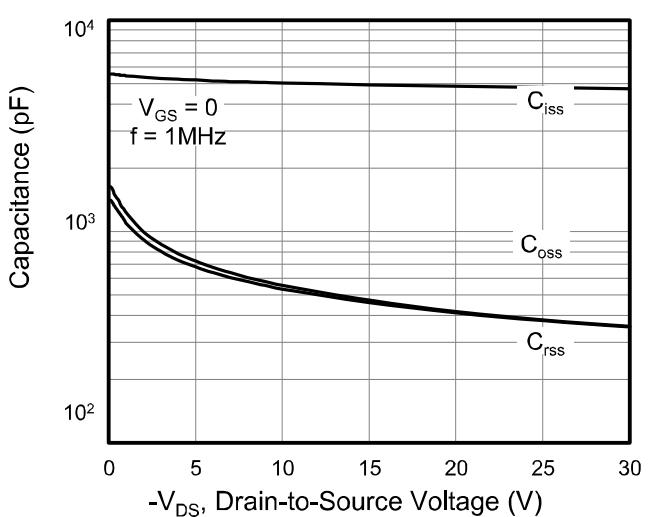


Figure 5. Gate Charge

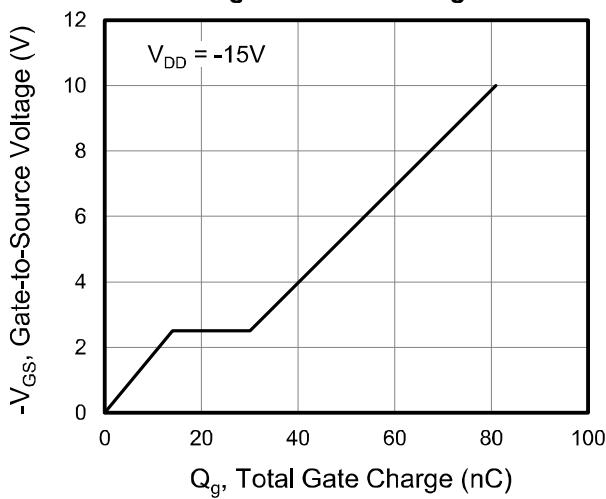
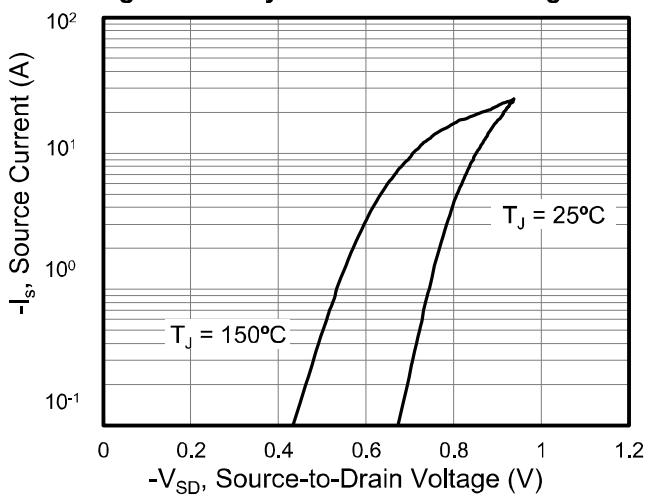


Figure 6. Body Diode Forward Voltage



4. Typical Characteristics (cont.)

Figure 7. On-Resistance vs. Junction Temperature

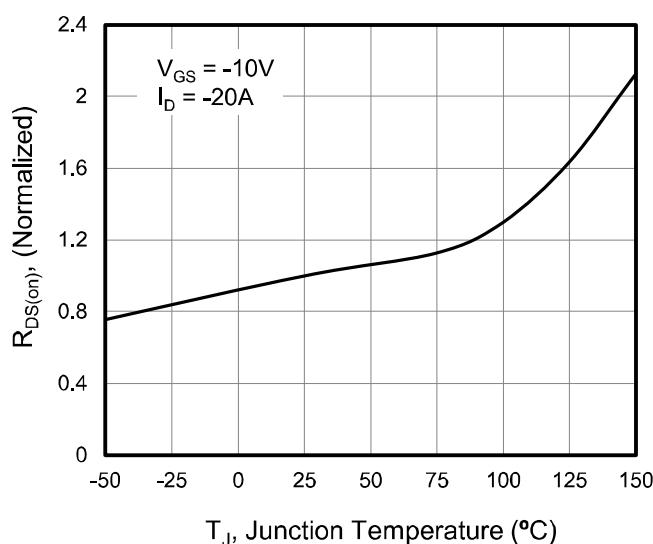


Figure 8. Threshold Voltage vs. Junction Temperature

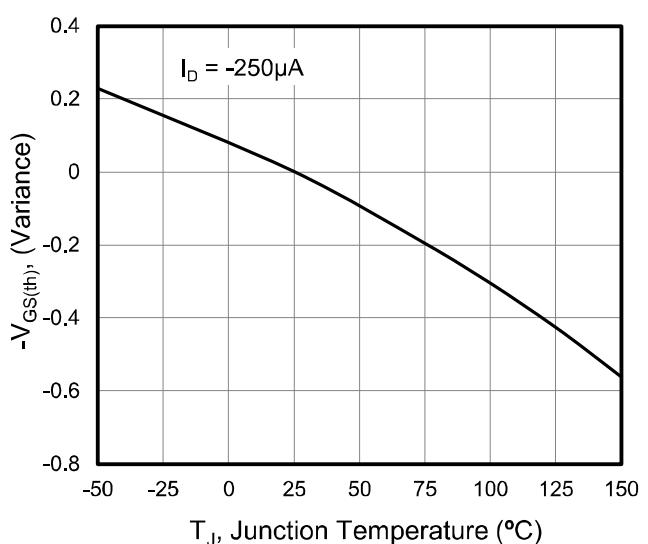


Figure 9. Transient Thermal Impedance

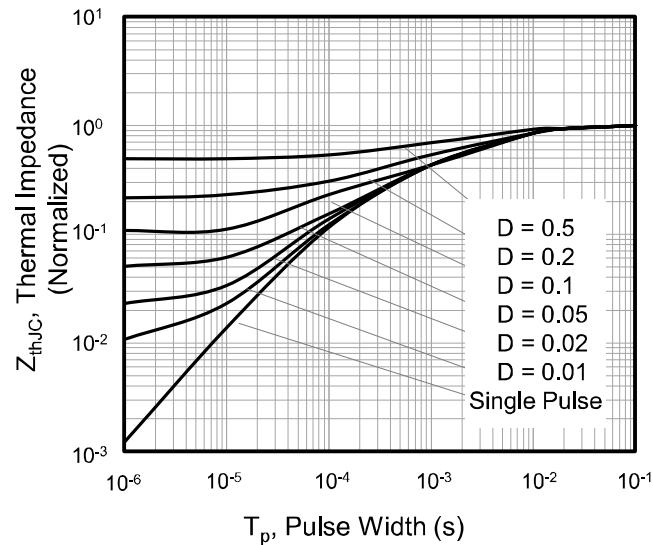


Figure 10. Safe operation area

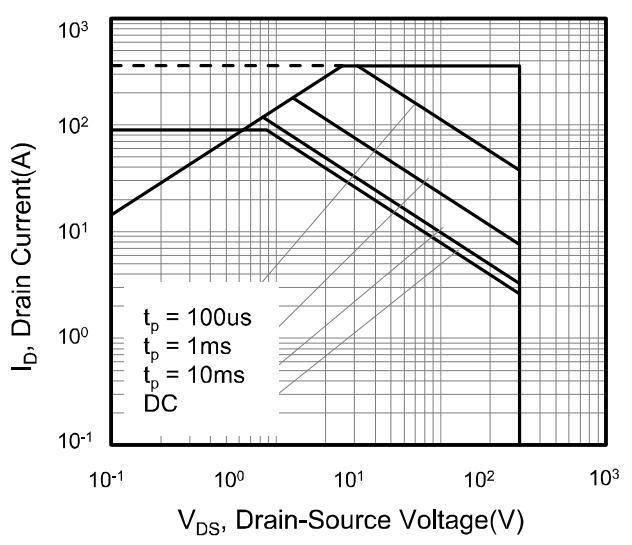


Figure A: Gate Charge Test Circuit and Waveform

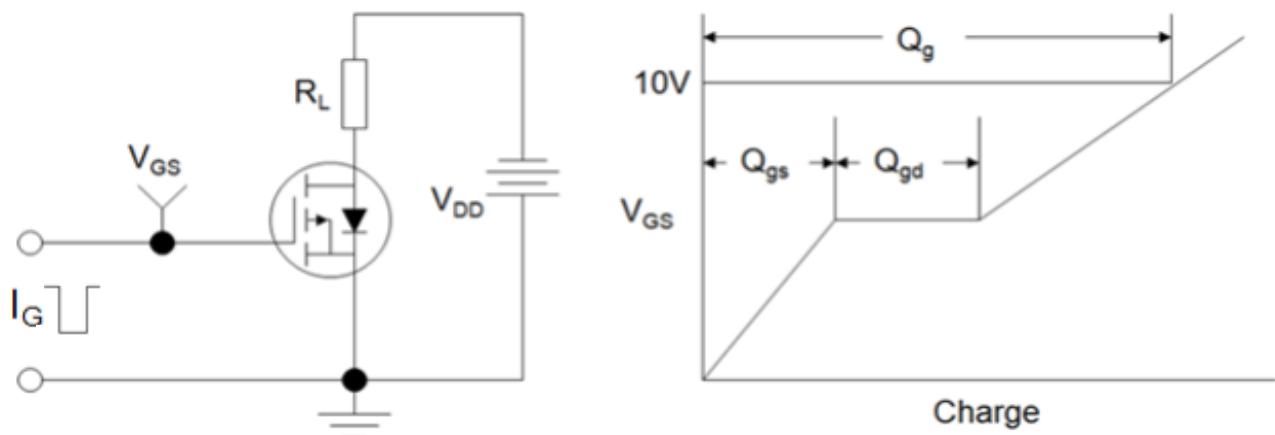


Figure B: Resistive Switching Test Circuit and Waveform

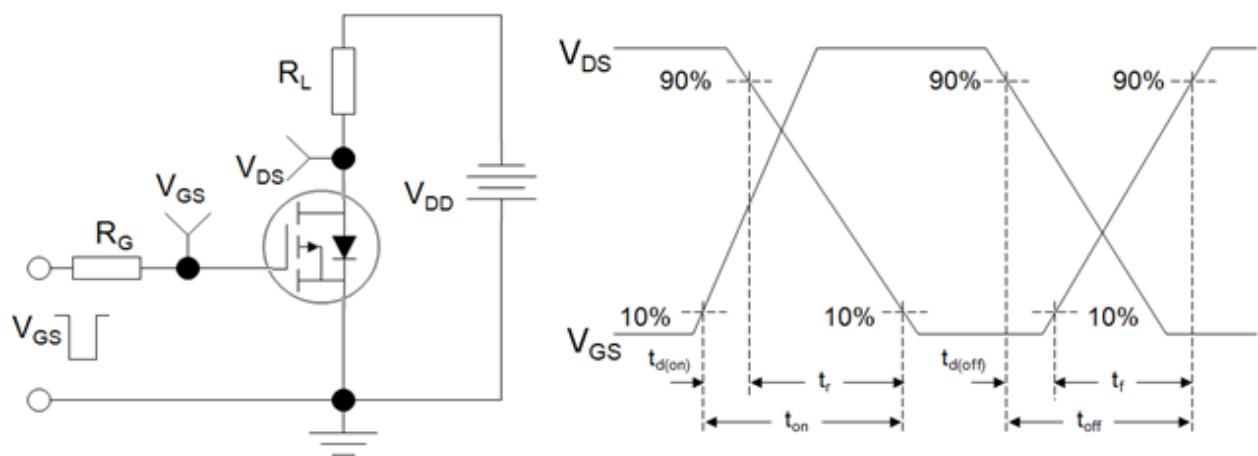
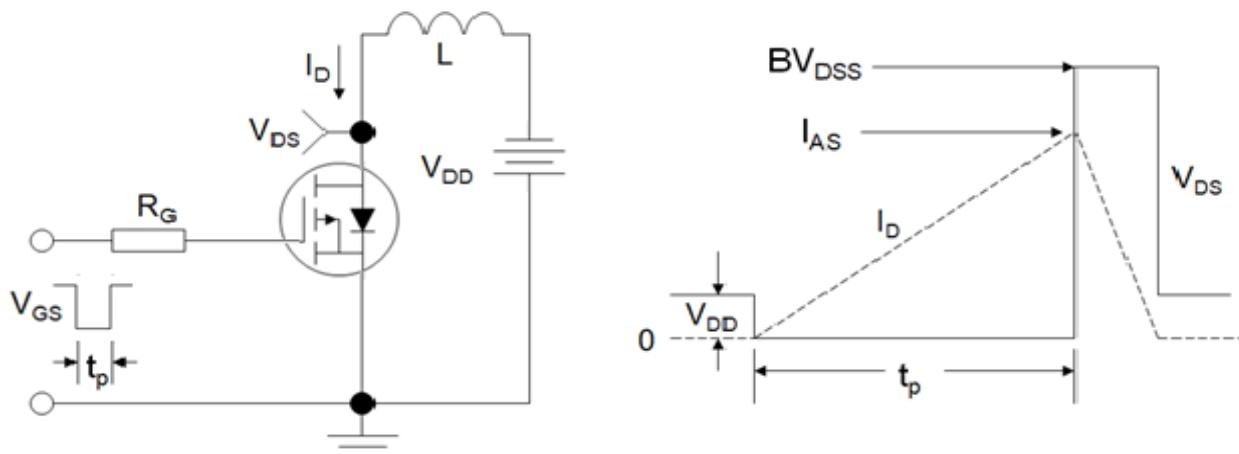
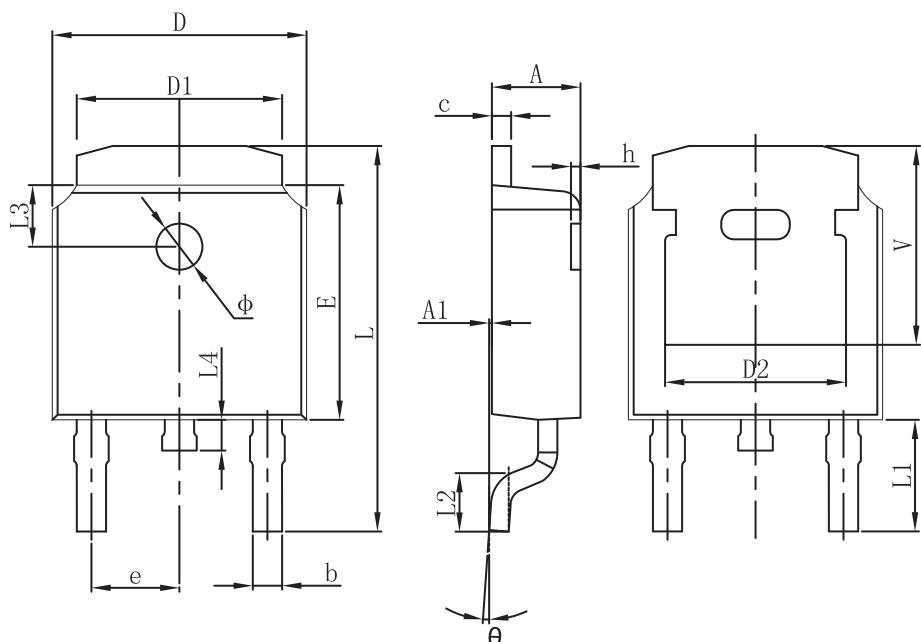


Figure C: Unclamped Inductive Switching Test Circuit and Waveform



5. Package Dimensions

TO-252 Package



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	2.200	2.400
A1	0.020	0.200
b	0.635	0.770
c	0.460	0.580
D	6.500	6.700
D1	5.100	5.460
D2	4.830 REF	
E	6.000	6.200
e	2.186	2.386
L	9.712	10.312
L1	2.900 REF	
L2	1.400	1.700
L3	1.600 REF	
L4	0.600	1.000
Φ	1.100	1.300
θ	0°	8°
H	0.000	0.300
V	5.250 REF	